

## Resin-moulded semiconductor hybrid module and manufacturing method thereof

Patent Number: EP0936671

Publication date: 1999-08-18

Inventor(s): KAMIMURA NORITAKA (JP); TAKAHASHI MASAAKI (JP); SAEKI JUNICHI (JP); TAMBA AKIHIRO (JP); YAMADA KAZUJI (JP); GOUDA MASAHIRO (JP); ISHII MAKOTO (JP); OGAWA TOSHIRO (JP); SUZUKI KAZUHIRO (JP)

Applicant(s): HITACHI LTD (JP)

Requested Patent:  EP0936671

Application Number: EP19990101733 19990211

Priority Number (s): JP19980029491 19980212

IPC Classification: H01L25/16, H01L23/433

EC Classification: H01L25/16H, H01L23/433E

Equivalents:  JP11233712,  US6291880

Cited Documents: EP0774782; US5699609; US5077595; JP8298299

### Abstract

A semiconductor device includes a main circuit part having a semiconductor device formed on an electrode plate (13) of a lead frame and a control circuit part having protective functions, which is integrally molded by a resin mold part (30) into an integral mold structure. 

Data supplied from the esp@cenet database - I2